

HMW65N045UF7

N-Channel eMOS UF7 Power MOSFET

650 V, 62.6 A, 45 mΩ

Description

The 650V eMOS UF7 series has ultra-fast body diode performance using E7 technology.

eMOS UF7 is Power Master Semiconductor's advanced fast recovery Super Junction MOSFET family by utilizing charge balance technology for excellent body diode performance, low on-resistance and reduced gate charge.

It combines the benefits of a fast switching performance with ease of usage and robustness. Additionally, we offer low reverse recovery time (trr) and reverse recovery charge (Qrr) for the bridge structure topology, especially for resonant converters (LLC, PSFB, etc.).

Features

BV_{DSS} @ $T_{J,max}$	I_D	$R_{DS(on),max}$	$Q_{g,typ}$
700 V	62.6 A	45 mΩ	142 nC

- Reduced Switching & Conduction Losses
- Fast Recovery Body-Diode
- Lower Gate Resistance
- 100% Avalanche Tested
- Pb-free and RoHS Compliant



Applications

- Soft Switching Topologies
- Telecom and Server Power Supplies
- EV Charger and Industrial Power Supplies

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Value	Unit	
V_{DSS}	Drain to Source Voltage		650	V	
V_{GSS}	Gate to Source Voltage		± 30	V	
I_D	Drain Current	Continuous ($T_C = 25^\circ\text{C}$)	62.6	A	
		Continuous ($T_C = 100^\circ\text{C}$)	39.6		
I_{DM}	Drain Current	Pulsed (Note1)	188	A	
E_{AS}	Single Pulsed Avalanche Energy		(Note2)	457	mJ
I_{AS}	Avalanche Current		(Note2)	8.4	A
E_{AR}	Repetitive Avalanche Energy		(Note1)	4.46	mJ
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt		(Note3)		
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	446	W	
		Derate Above 25°C	3.57		
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to 150	°C	
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds		260	°C	

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.28	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
HMW65N045UF7	HMW65N045UF7	TO-247	Tube	30 units

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

BV _{DSS}	Drain to Source Breakdown Voltage	V _{GS} = 0 V, I _D = 1 mA	650			V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700			
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V			10	μA
		V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125°C		57		
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 4.3 mA	3.0		5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 31.3 A		38.5	45	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0V, f = 250 kHz		5451		pF
C _{oss}	Output Capacitance		135			pF
C _{o(tr)}	Time Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		1477		pF
C _{o(er)}	Energy Related Output Capacitance		199			pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 31.3 A, V _{GS} = 10 V		142		nC
Q _{gs}	Gate to Source Charge		36			nC
Q _{gd}	Gate to Drain "Miller" Charge		74			nC
R _G	Gate Resistance	f = 1MHz		1		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DS} = 400 V, I _D = 31.3 A, V _{GS} = 10 V, R _G = 3.3 Ω See Figure 13		27		ns
t _r	Turn-On Rise Time			15		ns
t _{d(off)}	Turn-Off Delay Time			87		ns
t _f	Turn-Off Fall Time			11		ns

Source-Drain Diode Characteristics

I _S	Maximum Continuous Diode Forward Current			62.6		A
I _{SM}	Maximum Pulsed Diode Forward Current			188		A
V _{SD}	Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 31.3 A			1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 31.3 A, dI _F /dt = 100 A/μs		170		ns
Q _{rr}	Reverse Recovery Charge			1.3		μC

※Notes:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I_{AS} = 8.4 A, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 31.3 A, di/dt ≤ 100 A/μs, V_{DD} ≤ 400 V, starting T_J = 25°C.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

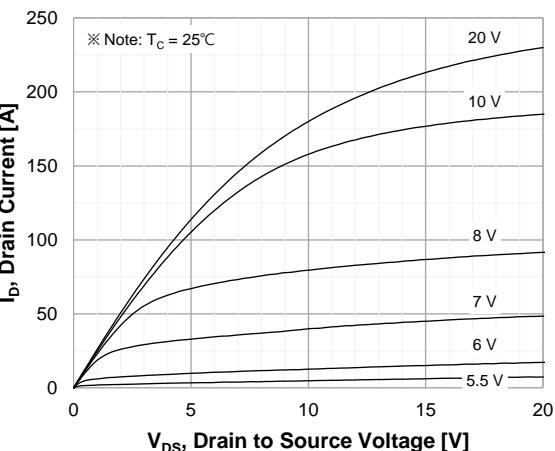


Figure 2. Transfer Characteristics

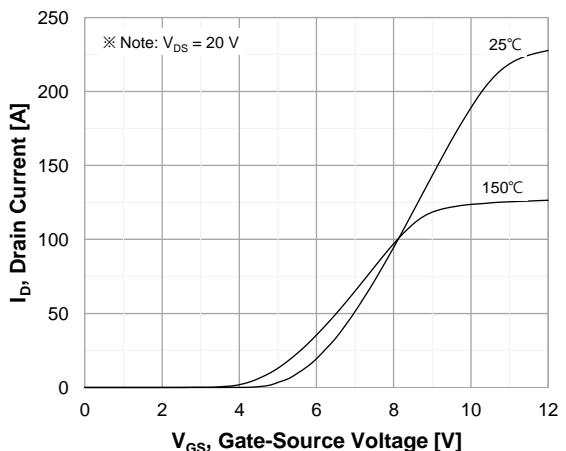


Figure 3. On-Resistance Characteristics vs. Drain Current and Gate Voltage

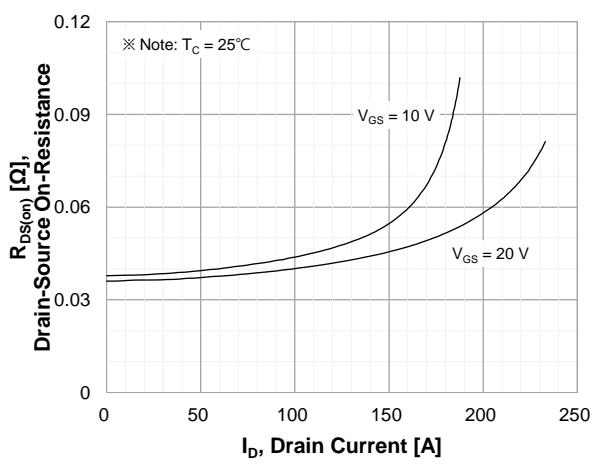


Figure 4. Diode Forward Voltage Characteristics vs. Source-Drain Current and Temperature

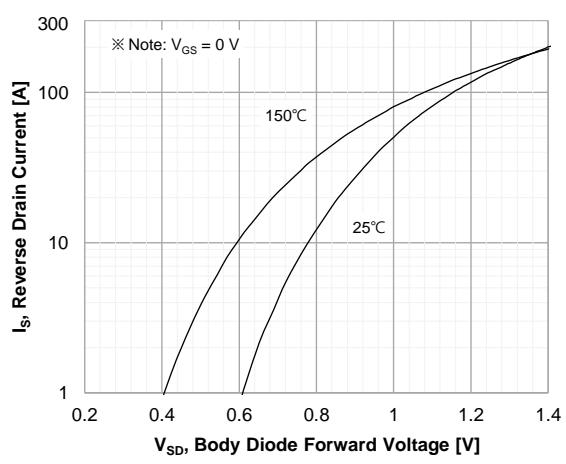


Figure 5. Capacitance Characteristics

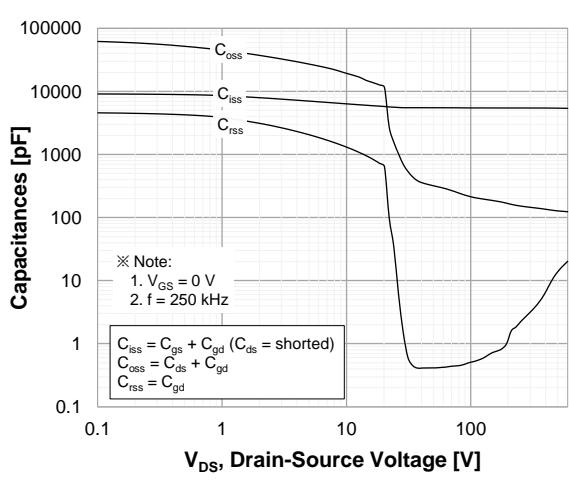
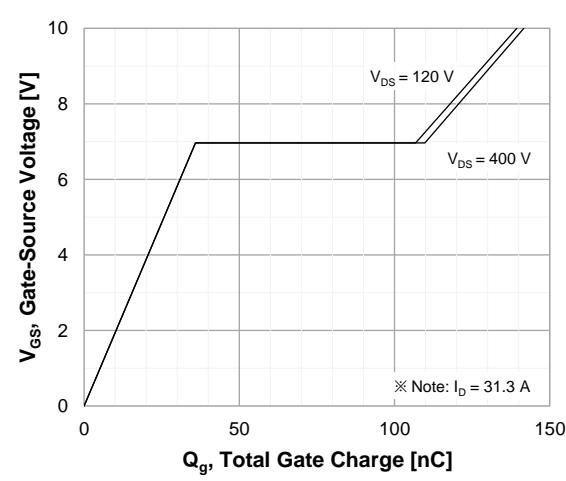


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics

Figure 7. Breakdown Voltage Characteristics vs. Temperature

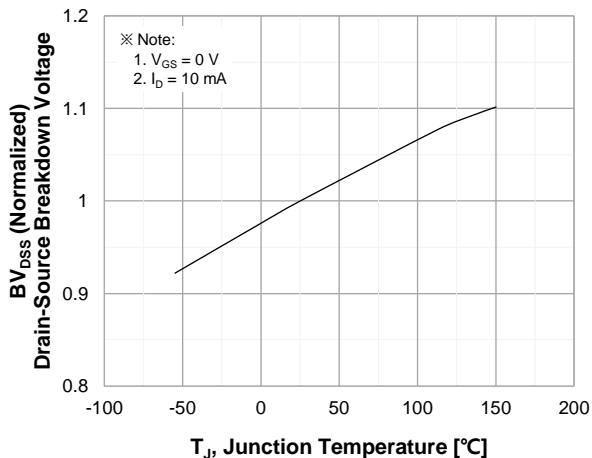


Figure 8. On-Resistance Characteristics vs. Temperature

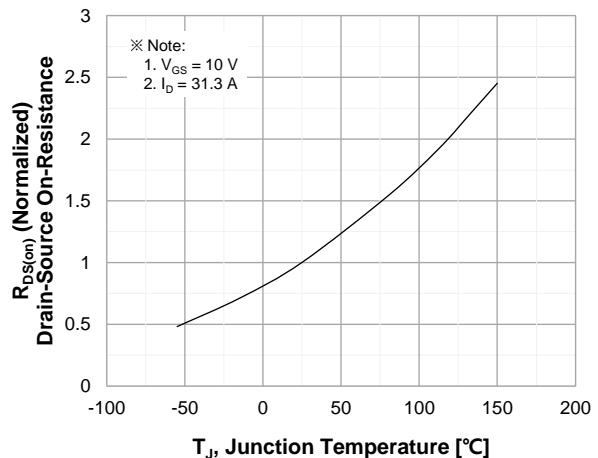


Figure 9. Maximum Safe Operating Area

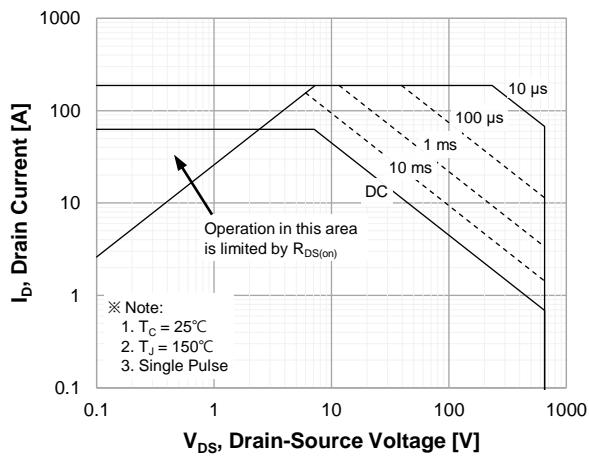


Figure 10. Maximum Drain Current vs. Case Temperature

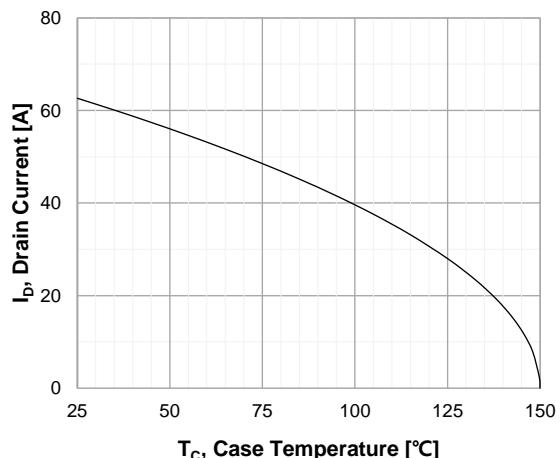


Figure 11. E_{oss} vs. Drain to Source Voltage

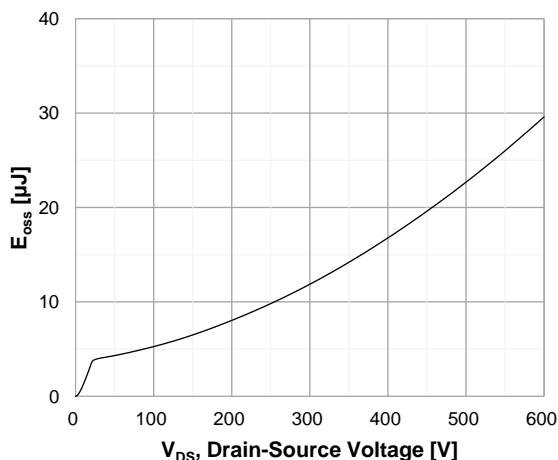
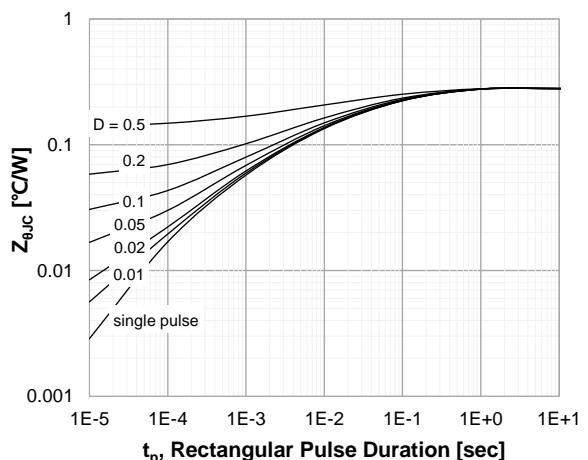


Figure 12. Transient Thermal Response Curve



Test Circuits

Figure 13. Inductive Load Switching Test Circuit and Waveforms

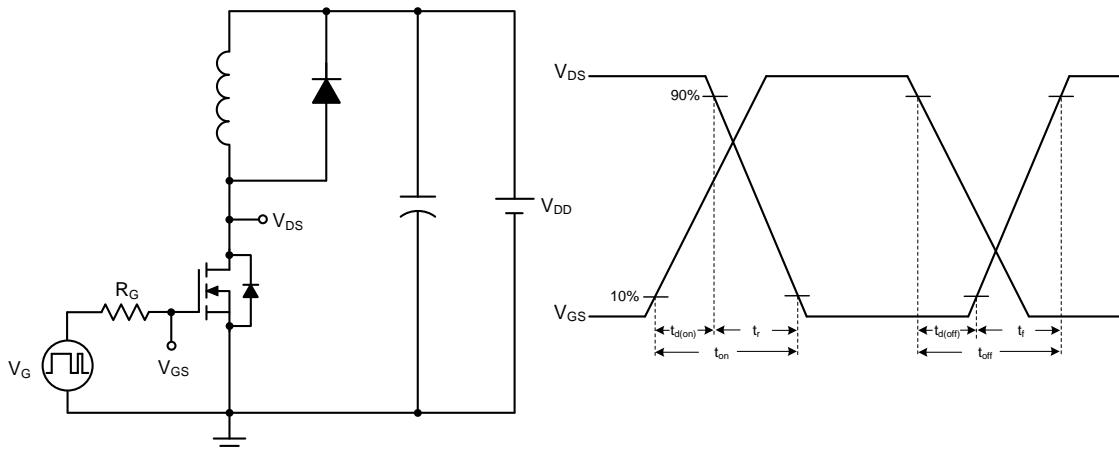


Figure 14. Unclamped Inductive Switching Test Circuit and Waveforms

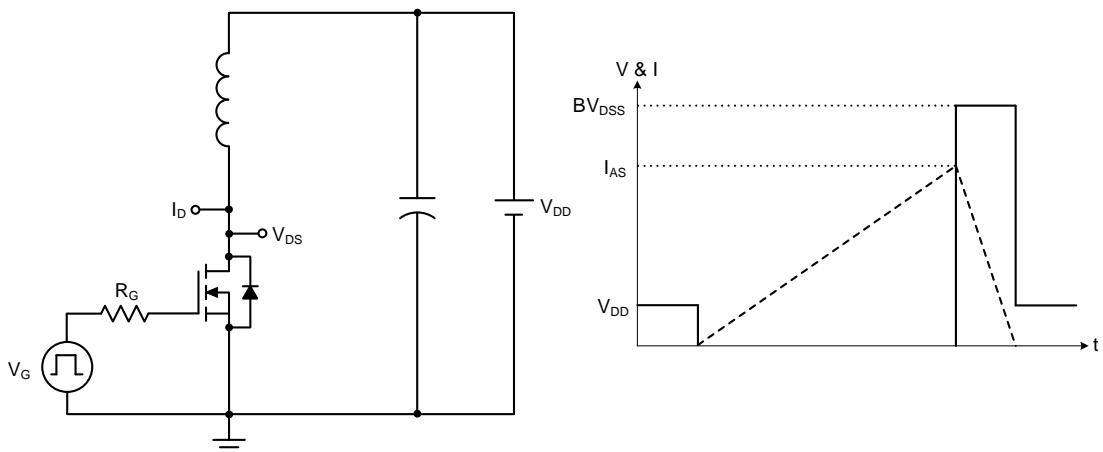
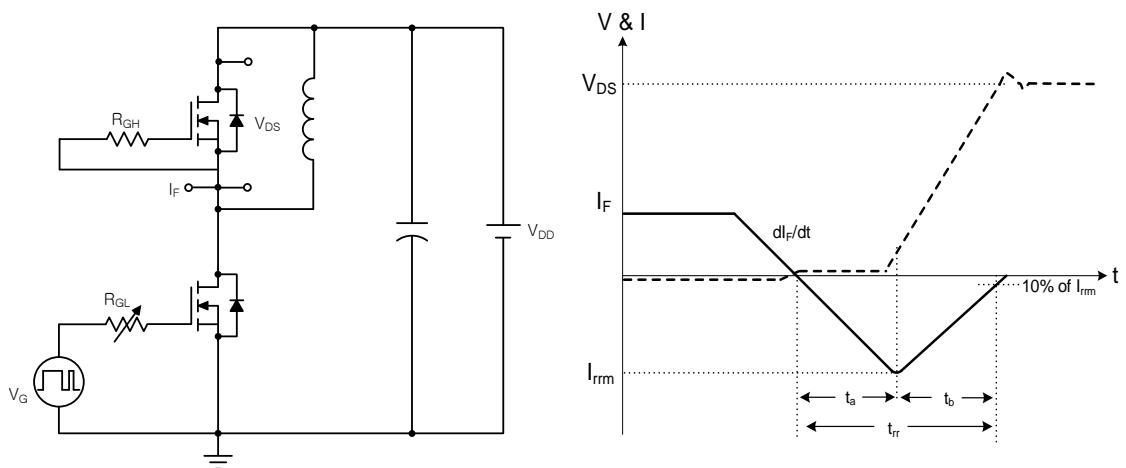
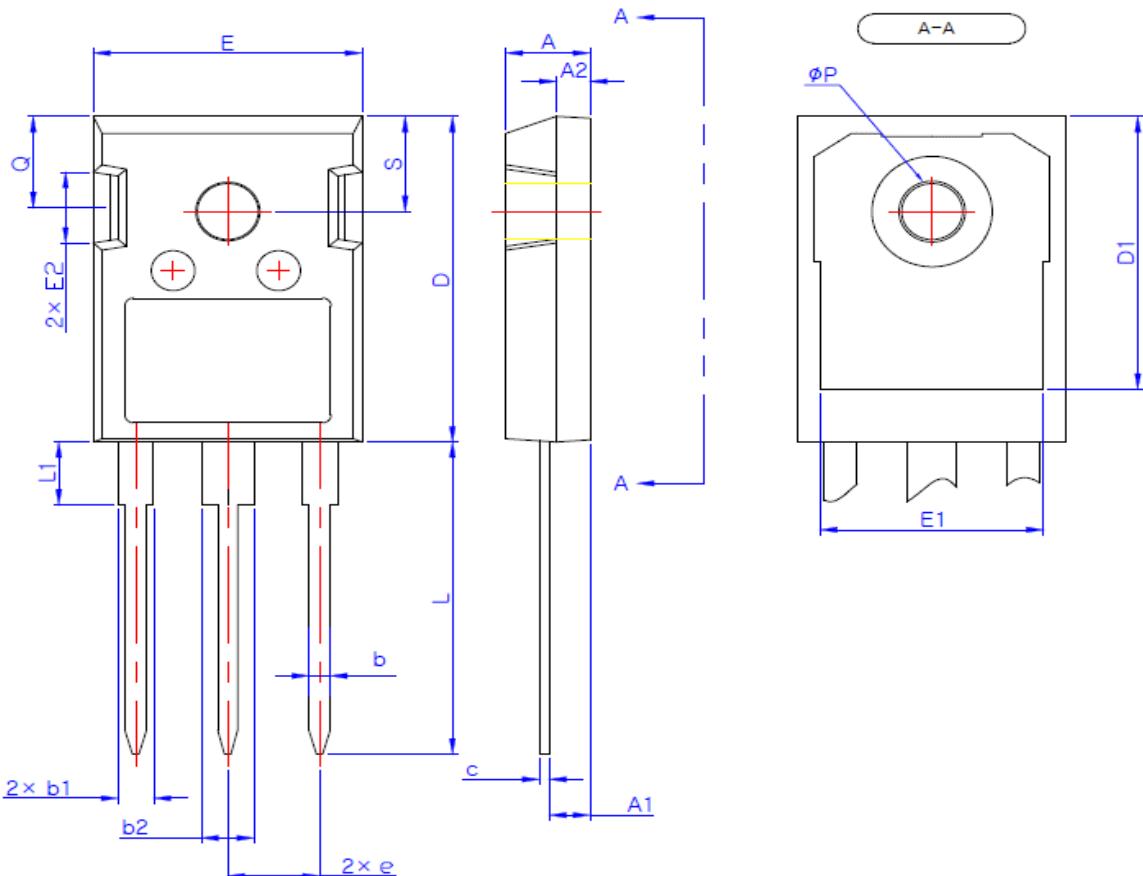


Figure 15. Peak Diode Recovery dv/dt Test Circuit and Waveforms



Package Outlines

TO-247



SYMBOL	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.29	2.42	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.91	2.06	2.20
b2	2.92	3.06	3.20
c	0.50	0.60	0.70
D	20.80	21.07	21.34
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.06	13.26	13.46
E2	4.32	4.58	4.83
e	5.45 BSC		
L	19.85	20.05	20.25
L1	4.05	4.27	4.49
ϕP	3.55	3.60	3.65
Q	5.59	5.89	6.19
S	6.15 BSC		

* Dimensions in millimeters